

AN11175

DALI master using LPC134x

Rev. 2 — 6 March 2013

Application note

Document information

| Info | Content |
|-----------------|---|
| Keywords | LPC134x, ARM, Cortex M3, DALI, USB, Building lighting |
| Abstract | This application note describes the use of the NXP LPC134x Cortex M3 microcontroller to create a DALI Master. |



Revision history

| Rev | Date | Description |
|-----|----------|--------------------|
| 2 | 20130306 | Editorial updates. |
| 1 | 20120301 | Initial version. |

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1. Document purpose

The purpose of this document is to explain the LPC1343 USB to DALI demo board. Both the hardware and software are described in detail.

This document is intended for technical persons, such as system architects and hardware/software engineers, interested in designing/developing a DALI master using NXP microcontrollers.

For creating a DALI setup with the LPC1343 USB to DALI demo board, refer to “UM10553 DALI getting starting guide” [\[3\]](#). The board is available from NXP as OM13046, 12NC: 935299079598.

2. Introduction

The DALI master is an example implementation for a USB enabled DALI controller, built using the NXP LPC134x microcontroller. The DALI master features a USB Human Interface Device (HID) interface, which means that no dedicated software driver needs to be installed on the host PC. The USB, GPIO and 32-bit timer/counter of the LPC134x MCU are the main hardware blocks used to implement the DALI master.

The software can be built with

- LPCXpresso v5.0.10_1066, and
- IAR Embedded Workbench for ARM v6.40.

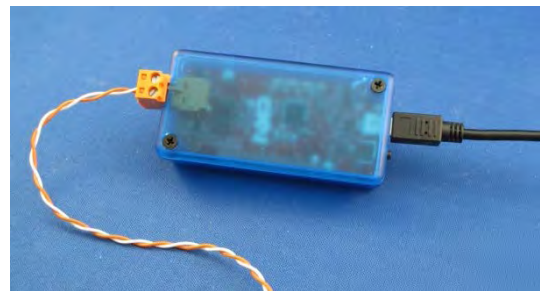


Fig 1. OM13046 USB to DALI Master assembled PCB

For background information on the DALI standard, we refer to IEC62386-102 [\[1\]](#).

This USB to DALI design can be used together with an LPC111x DALI slave design presented in AN11174 [\[4\]](#). Furthermore, UM10553 [\[3\]](#) describes how to use the USB to DALI master together with the LPC111x DALI slave and a windows PC GUI for control.

3. DALI master hardware

3.1 Overview

The schematic of the DALI master is shown in [Fig 2](#).

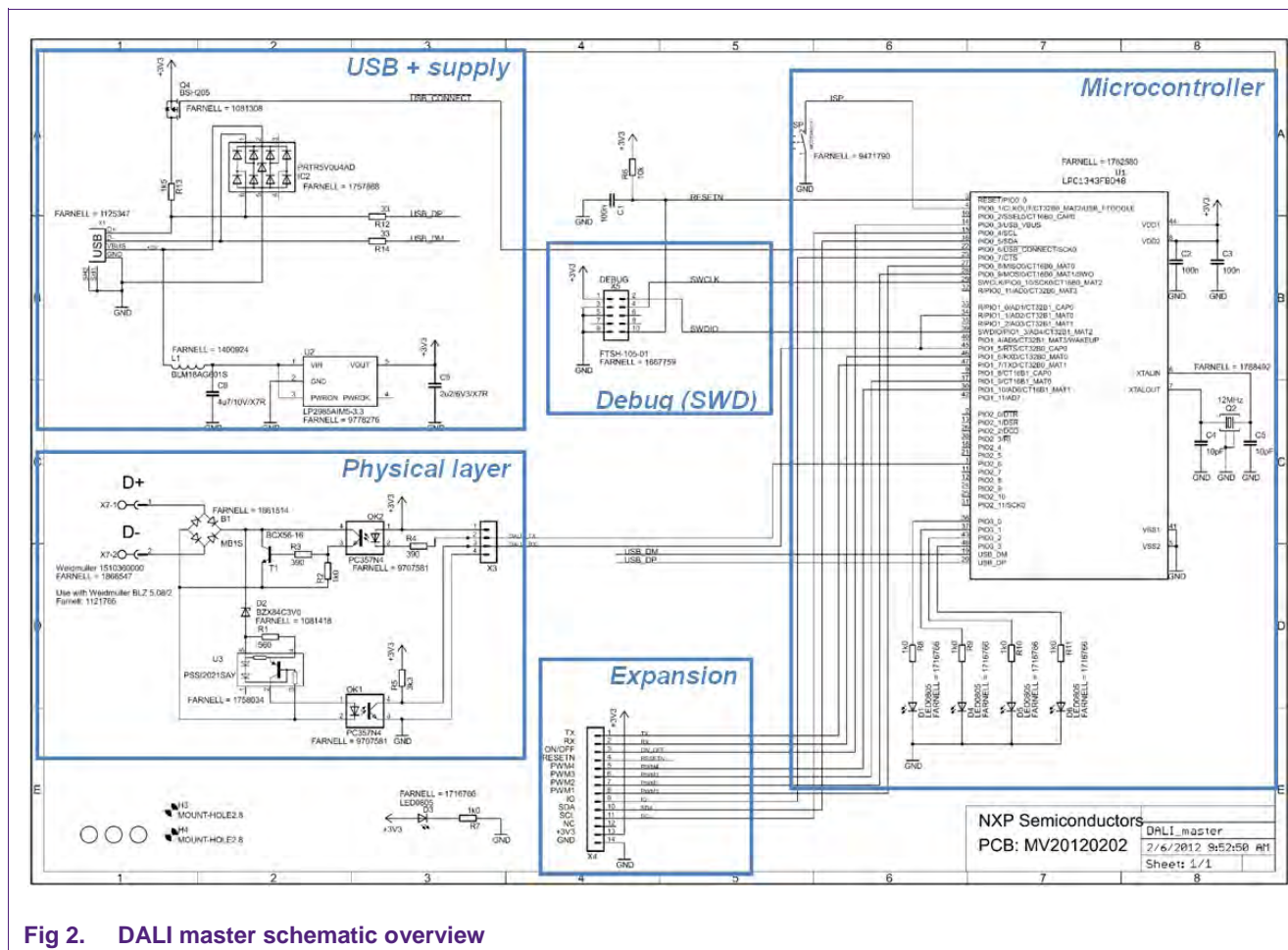


Fig 2. DALI master schematic overview

3.2 Physical layer

The physical layer is an example circuit and does not fully comply with the DALI specification. The circuit is not protected for mains voltage and therefore does not comply with the overvoltage protection test (62386-102 © IEC:2009: 12.1.4.2 Test sequence 'Overvoltage protection').

The DALI bus connects to the connections D+ and D- of the DALI connector. The connector is a Weidmüller header used with a Weidmüller socket block. The connection is polarity independent.

The DALI physical layer is isolated using opto-couplers from the rest of the electronics.

The design is made polarity independent by using bridge rectifier B1. Both terminals D are interchangeable.

The transmission part of the DALI slave is created with T1, R2, R3, OK2 and R4. The microcontroller drives signal DALI1_TX at 0 V or 3.3 V. For low signals of DALI1_TX, Optocoupler OK2 connects junction R2 and R3 to the DALI bus, which creates a drive

current for the base of T1 that starts to conduct and short circuit the DALI bus via bridge B1. When the signal DALI1_TX is high, transistor T1 does not conduct and the bus is in the 'high' state. Resistor R3 (390 Ohm) allows T1 to become saturated and creates a low voltage level on the bus while having a low voltage drop on T1. This keeps the power dissipation of T1 limited as it should be able to sink the maximum DALI bus current of 250 mA; for this reason T1 should have a high h_{FE} of minimum 100. In this way, no additional mounting area for cooling area is needed.

The reception path is created around optocoupler OK1, U3, R1, R5 and Zener diode D2. When the DALI bus is idle (high), a constant current source of about 1 mA is created using U1 and R1. This current is used to drive optocoupler OK1 that signals the level of the DALI bus to the microcontroller via DALI1_RX. The current source limits the maximum current load the circuit creates when not in transmission mode. Zener D2 and bridge rectifier B1 drop the received bus voltage to a level to guarantee that a low level voltage of 6.5 V does not drive the optocoupler.

The circuit around OK1 and R3 creates an inverted signal to the microcontroller; a high DALI bus level will connect DALI1_RX to low. A low DALI bus level creates a high signal on DALI1_RX.

All components are chosen to withstand several factors (70 V to 80 V) of the highest allowed DALI bus voltage level of 22.5 V. The physical layer does not contain overvoltage protection or suppression components; overvoltage protection is the user's responsibility.

The optocouplers create isolation between the microcontroller side and the DALI bus. The isolation is sufficient for evaluation of the DALI software stack when the microcontroller is connected in a non-isolated way to the mains supply. Any re-use of this design should be made compliant to the isolation requirements as specified in [IEC62383-101] section 5.4 [\[1\]](#).

3.3 Microcontroller

The system is built around NXP's LPC1343 device, which is a Cortex-M3 running at frequencies of up to 72 MHz.

Included are a USB 2.0 Full-Speed device controller, 32 kB on-chip Flash, 8 kB SRAM, UART, SSP, I2C, ADC, etc.

Debugging and flashing connection is provided by header X5, which complies with the 10-pin SWD standard supported by many flash and software tools.

If the device is connected to USB while the ISP push button is pressed, the DALI Master connects as a Mass Storage device to the PC. This allows programming via drag and drop of a binary image onto the DALI Master via a file explorer.

Four LEDs are provided for general purpose use (e.g. status information). One of the LEDs is used to signal DALI bus transmission when the DALI master sends data to the bus.

3.4 USB + Supply

The USB interface uses a mini-AB socket.

The connection to the USB is accomplished by bringing USB_D+ (for a full-speed device) HIGH through a 1.5 kOhm pull-up resistor via a FET. The USB SoftConnect feature can be used to allow software to finish its initialization sequence before deciding to establish connection to the USB. Re-initialization of the USB bus connection can also be performed without having to unplug the cable.

Extra ESD protection is provided with IC2.

3.5 Expansion

An expansion header X4 (optional) can be mounted to provide extra connections to the microcontroller.

3.6 Board Layout

The layout of the board (74.0 mm x 34.0 mm) is given below.

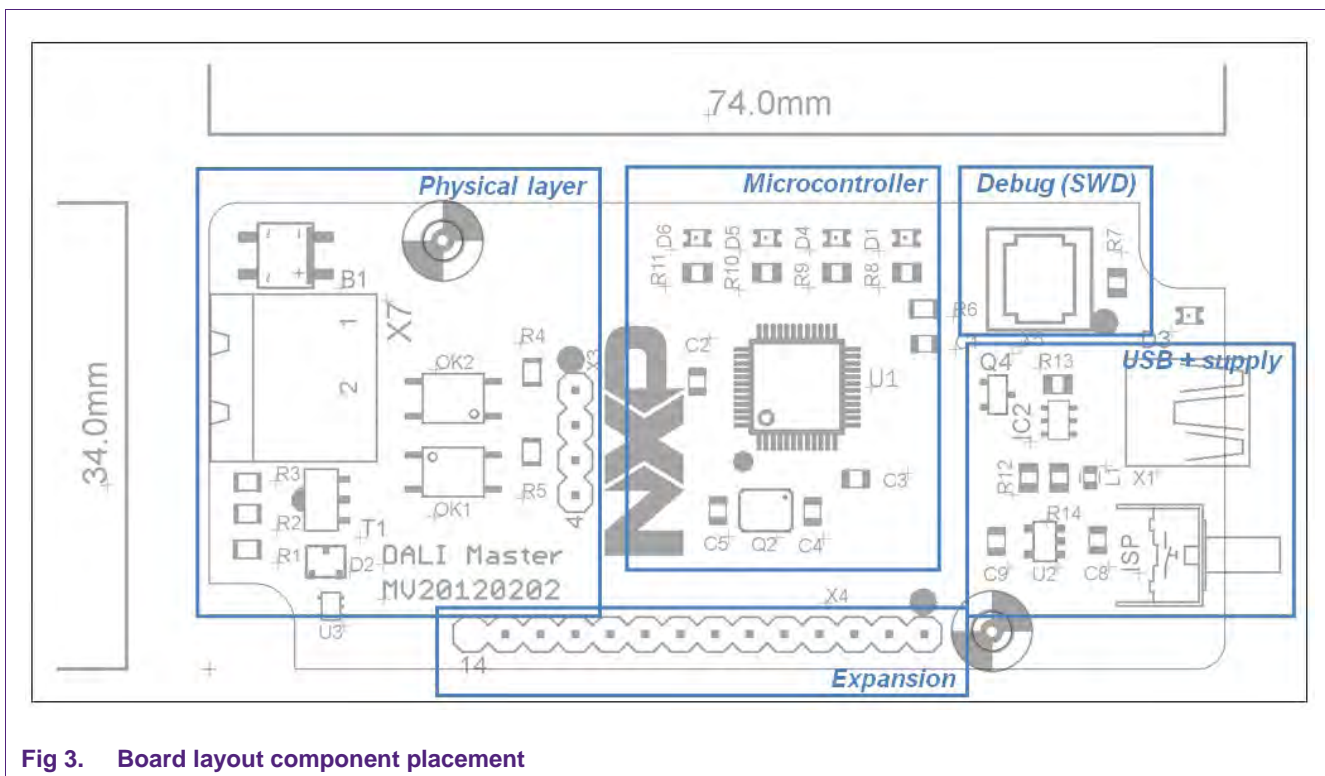


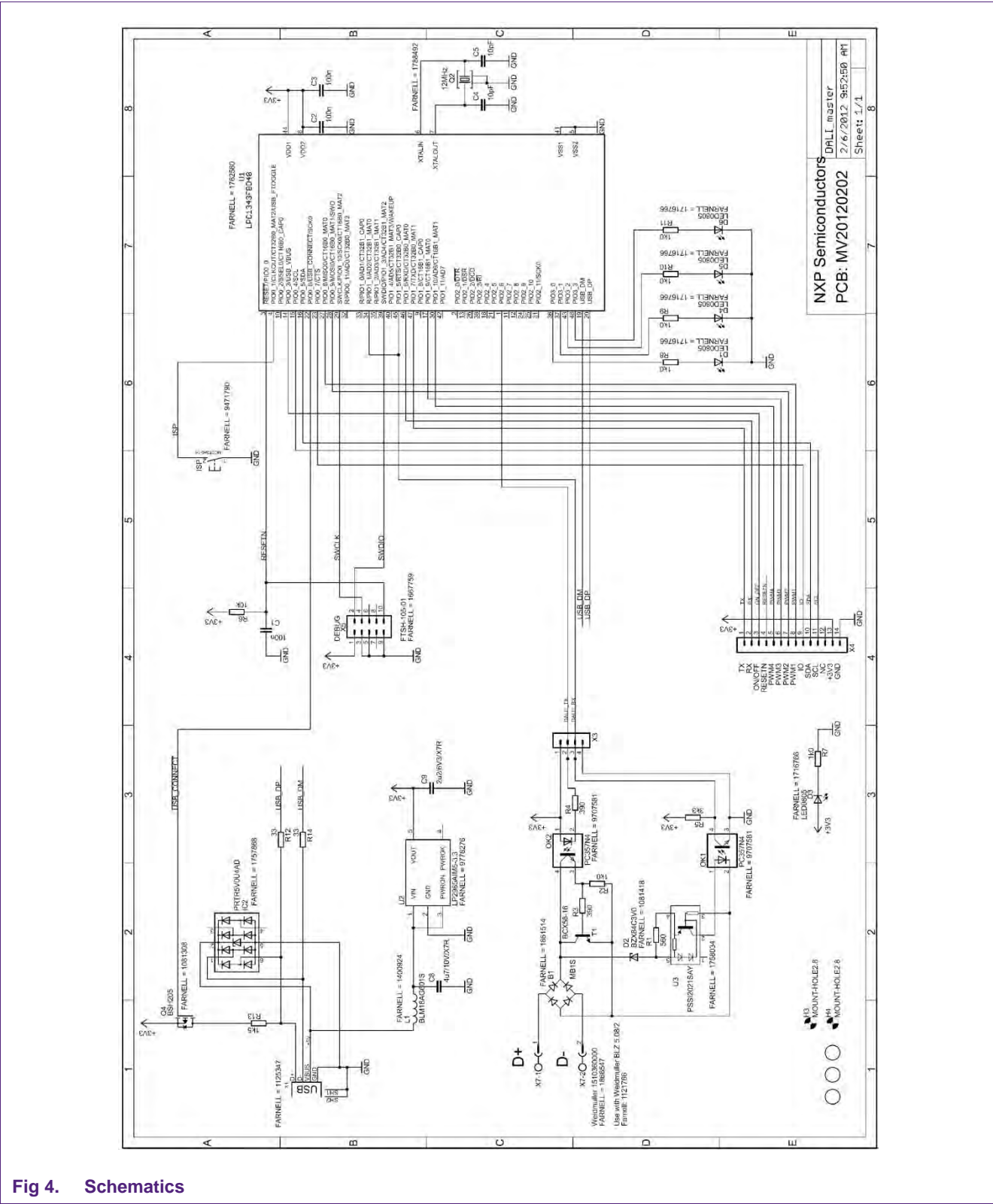
Fig 3. Board layout component placement

Table 1. DALI master parts list

| Part | Value | Device | Package | Description | Farnell |
|------|-------------|-----------------|--------------------------------|---|---------|
| B1 | MB1S | MB1S | SOIC-4 | Bridge Rectifier | 1861514 |
| C1 | 100n | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C2 | 100n | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C3 | 100n | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C4 | 10pF | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C5 | 10pF | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C8 | 4u7/10V/X7R | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| C9 | 2u2/6V3/X7R | C-EUC0603 | C0603 | CAPACITOR, European symbol | |
| D1 | LED0805 | LEDCHIPLED_0805 | CHIPLED_0805 | LED | 1716766 |
| D2 | BZX84C3V0 | BZX84CSMD | TO236 | Z DIODE | 1081418 |
| D3 | LED0805 | LEDCHIPLED_0805 | CHIPLED_0805 | LED | 1716766 |
| D4 | LED0805 | LEDCHIPLED_0805 | CHIPLED_0805 | LED | 1716766 |
| D5 | LED0805 | LEDCHIPLED_0805 | CHIPLED_0805 | LED | 1716766 |
| D6 | LED0805 | LEDCHIPLED_0805 | CHIPLED_0805 | LED | 1716766 |
| IC2 | PRTR5V0U4AD | PRTR5V0U4AD | ESD-PROTECTION_SOT457R_PHILIPS | | 1757868 |
| ISP | MCDTSA6-5K | MCDTSA6 | TACT90L | | 9471790 |
| L1 | BLM18AG601S | L0603 | P0603 | | 1400924 |
| OK1 | PC357N4 | PC357N4TJ00F | PC357N | Optocoupler, Phototransistor Output | 9707581 |
| OK2 | PC357N4 | PC357N4TJ00F | PC357N | Optocoupler, Phototransistor Output | 9707581 |
| Q2 | 12MHz | CRYSTAL4 | XTAL4 | | 1788492 |
| Q4 | BSH205 | BSH205 | SOT23 | P-channel enhancement mode MOS transistor | 1081308 |
| R1 | 560 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R2 | 1k0 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R3 | 390 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R4 | 390 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R5 | 3k3 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R6 | 10k | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R7 | 1k0 | R-EU_R0805 | R0805 | RESISTOR, European symbol | |
| R8 | 1k0 | R-EU_R0805 | R0805 | RESISTOR, European symbol | |

| Part | Value | Device | Package | Description | Farnell |
|------|-----------------|---------------------|---------------------------------|---|---------|
| R9 | 1k0 | R-EU_R0805 | R0805 | RESISTOR, European symbol | |
| R10 | 1k0 | R-EU_R0805 | R0805 | RESISTOR, European symbol | |
| R11 | 1k0 | R-EU_R0805 | R0805 | RESISTOR, European symbol | |
| R12 | 33 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R13 | 1k5 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| R14 | 33 | R-EU_R0603 | R0603 | RESISTOR, European symbol | |
| T1 | BCX56-16 | BC868-NPN-SOT89-BCE | SOT89-BCE | NPN Transistor | |
| U1 | LPC1343FBD48 | LPC1343FBD48 | LQFP48 | NXP Semiconductors | 1762580 |
| U2 | LP2985AIM5-3.3 | LP2985AIM5 | SOT23-5 | V REG LDO +3.3V | 9778276 |
| U3 | PSSI2021SAY | PSSI2021SAY | SOT353 | Constant current source in SOT353 package | 1758034 |
| X1 | USB | USB | USB-MB-H2 | | 1125347 |
| X3 | Pin header 4x1 | MA04-1R | MA04-1R | PIN HEADER | |
| X4 | Pin header 14x1 | MA14-1 | MA14-1 | PIN HEADER | |
| X5 | FTSH-105-01 | FTSH-105-01 | CON-SAMTEC_FTSH-105-01-XXX-DV-K | | 1667759 |
| X7 | Header 2p | | | Weidmuller 1510360000 | 1866547 |
| X7a | Socket block 2p | | | Weidmuller BLZ 5.08/2 | 1121766 |

3.7 DALI master schematics



4. DALI master software

4.1 Architecture

The software of the DALI master uses the USB HID software driver located in the boot ROM of the LPC134x. The software running on the DALI master does not incorporate a Real Time Operating System; this allows the memory footprint of the firmware to remain as small as possible. The software is written in the “C” programming language.

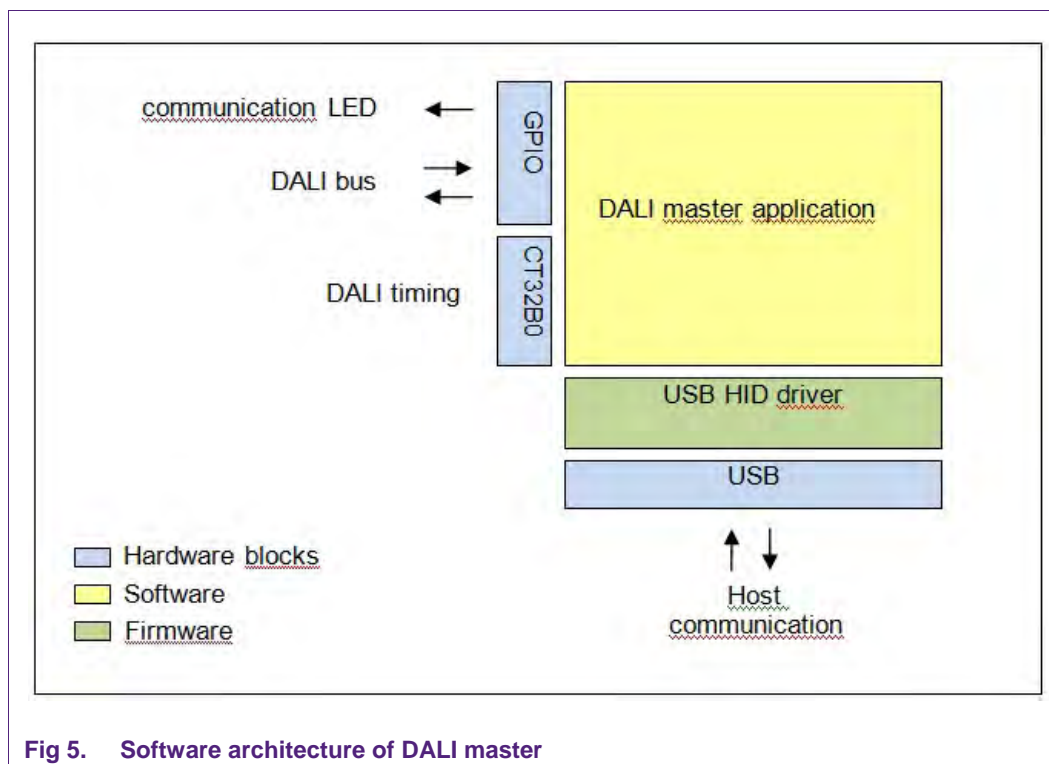


Fig 5. Software architecture of DALI master

The software of the DALI master enables it to function as a controller on the connected DALI bus.

4.2 Main software execution flow

[Fig 6](#) shows the flowchart of the DALI master software. The DALI master initialization is described in [section 4.3](#). The host can invoke a command via USB to the DALI master which puts this command on the DALI bus. When an answer is expected, the DALI master gets the answer from the DALI bus and passes it back to the host via the USB interface.

Interfacing from the DALI master application with the USB HID software driver is via two callback functions: `DALI_SetOutReport()` and `DALI_GetInReport()`. The OutReport holds the forward frame (one address byte, plus one data byte) as sent by the host. The InReport holds the backward frame to be sent to the host. When the DALI master is busy on the DALI bus, the LED on the PCB will be on, and it won't accept a new command from the host. The value of the forward frame defines whether the DALI master will put the command only one time or two times (repeat) on the DALI bus.

The actual data that is put on the DALI bus is defined as follows:

- One start bit (logic 1, bi-phase coded)
- One address byte (bi-phase coded)
- One data byte (bi-phase coded)
- Two stop bits (idle line)

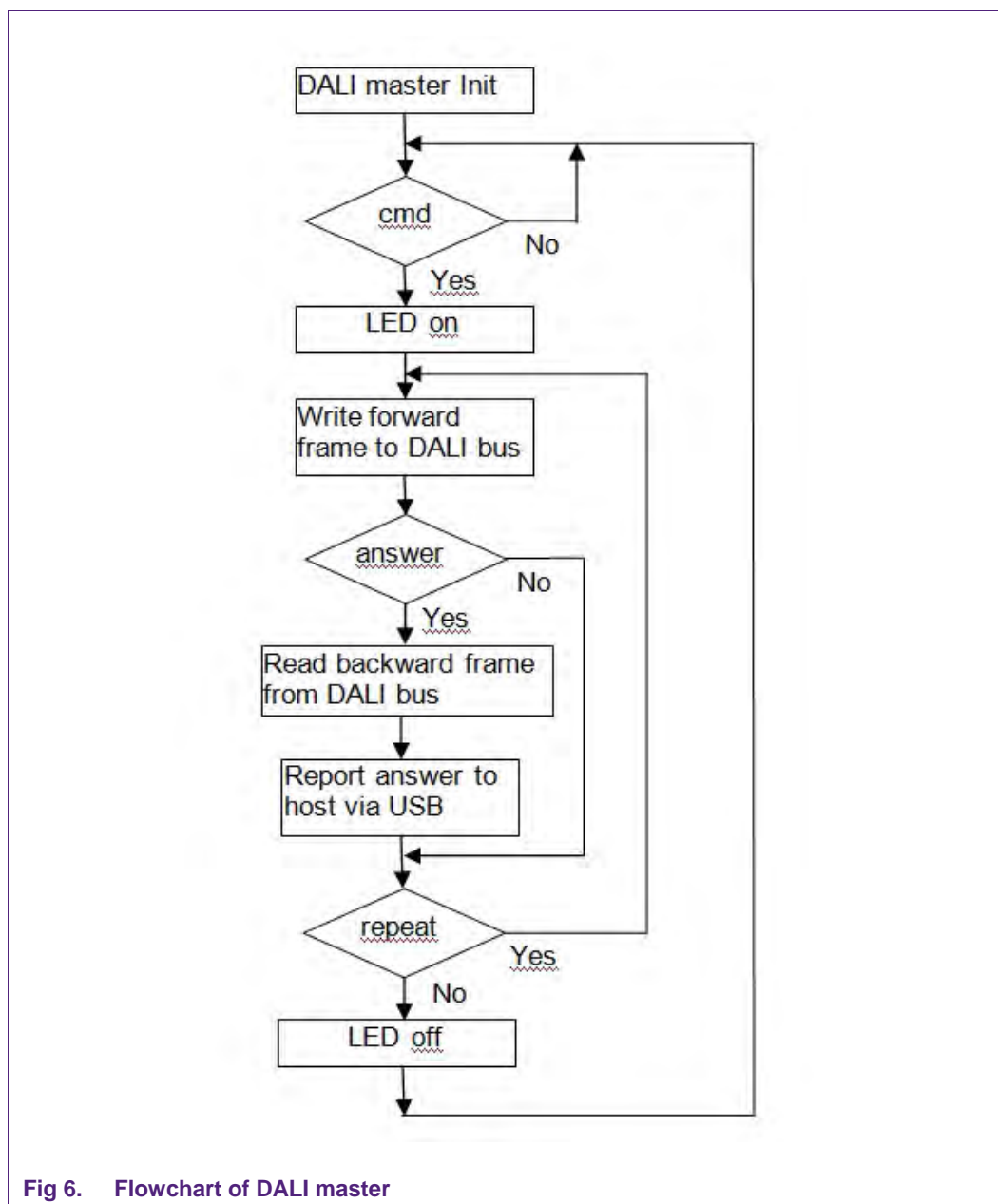


Fig 6. Flowchart of DALI master

The forward frame is bi-phase (Manchester) encoded before it is put on the DALI bus. A logic 1 bit of the forward frame is encoded as symbol "01"; a logic 0 bit of the forward frame is encoded as symbol "10". The DALI information rate is 1200 bit/s, and the symbol rate on the DALI bus is 2400 symbols/s. [Fig 7](#) shows a DALI transmission between two devices on the bus.

One 32-bit timer is used to put the symbols on the DALI bus at the correct time. PIO pin P2.6 of the LPC134x drives the DALI transmit line; PIO pin P1.1 monitors the DALI receive line.

The first symbol (first half of start bit) is put on the DALI bus by the main loop of the DALI master software and the remaining 37 symbols (one start bit symbol + 32 forward frame symbols + four stop bits symbols) are put on the DALI bus by the timer interrupt handler. When transmitting all the symbols on the DALI bus is finished, the timer interrupt handler captures the optional response symbols from a DALI slave.

The capture unit (part of the 32-bit timer hardware block in the LPC134x) detects a change in the line value on the DALI receive pin, which then generates an interrupt. This causes the timer interrupt handler to store the line value and the time offset since the start of the DALI slave answer. When the timer signals the end of the answering time window, the timer interrupt handler takes care of DALI bus idle timing. When the timer interrupt handler finishes its work, the main loop continues to decode the received symbols from the DALI slave and returns this answer back to the host.

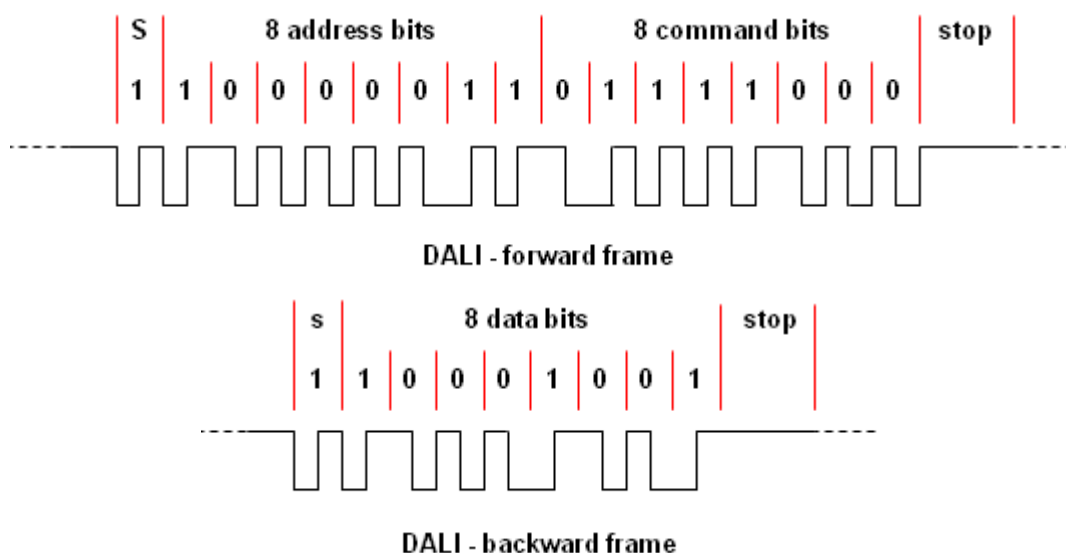


Fig 7. Example of DALI data on the bus

4.3 Initialization sequence

The following occurs when the DALI master is powered: the LPC134x microcontroller starts up, the stack pointer is loaded with the value from address 0:3, and the program counter is loaded with the value from address 4:7 (the address of the reset handler). This results in the calling of main().

The main() function directly calls the function SystemInit(), and after that the function DALI_Thread() is called. SystemInit() sets up the main PLL that is used to set the proper CPU clock, as configured by LPC_CORE_CLOCKSPEED_HZ in 'app_config.h'. Function SystemInit() is from the CMSIS library. The function DALI_Thread() implements the endless loop which handles the USB communication and transmits/receives data to/from the DALI bus. Before the endless loop is entered, the LPC I/O pins for driving the DALI bus are setup, the timer hardware block is initialized, the timer interrupt is enabled, the USB HID driver is initialized, and the LPC output pin for controlling the LED is configured.

4.4 USB HID driver

The USB HID driver is placed in the boot ROM of the LPC134x, and can't be changed by the user. The DALI master software has a very thin glue layer to initialize this USB HID driver, and to register the callback functions InReport() and OutReport().

4.5 Interrupts

The following table shows the interrupts that are handled by the software.

Table 2. DALI master used interrupts

| Interrupt | Description |
|-----------|---|
| USB_IRQ | Generated by the USB HW block. Used for transmitting/receiving data to and from the host. |
| TIMER_IRQ | Generated by the 32-bit timer HW block. Used for transmitting/receiving data to and from the DALI bus. |

4.6 Software source code files

The software tree holding the source code files of the DALI master is shown in [Fig 8](#).

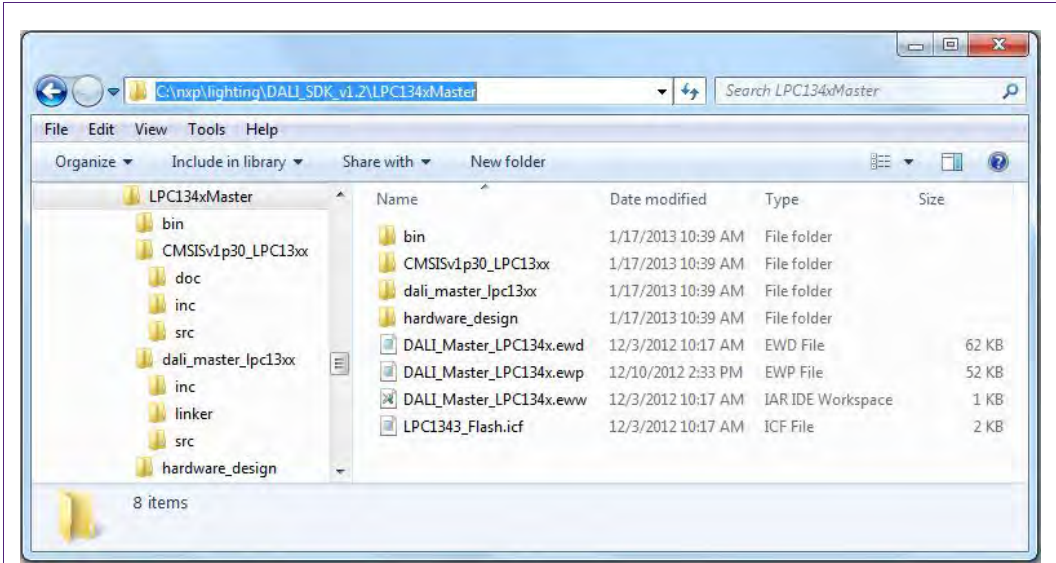


Fig 8. Software tree of DALI master

All DALI master source code is contained in the directory DALI_Master, which consists of a “CMSIS” directory containing the CMSIS source code; a “dali_master_lpc13xx” directory containing the source code of the DALI master; and the project files of the IAR IDE.

[Fig 9](#) shows the contents of the “dali_master_lpc13xx\src” directory, while [Fig 10](#) shows the contents of the “dali_master_lpc13xx\inc” directory.

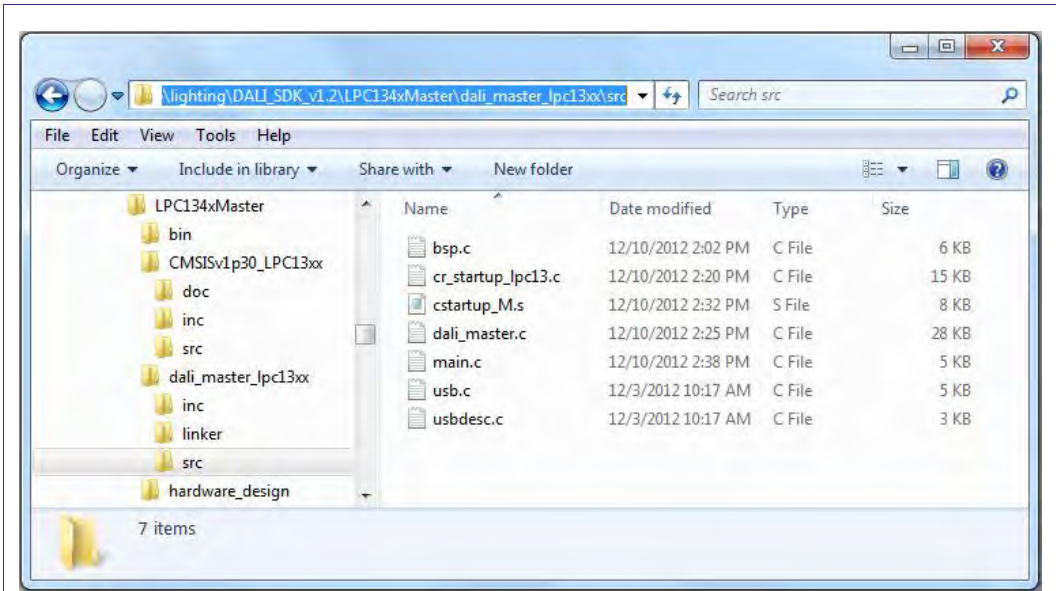


Fig 9. DALI master source code files

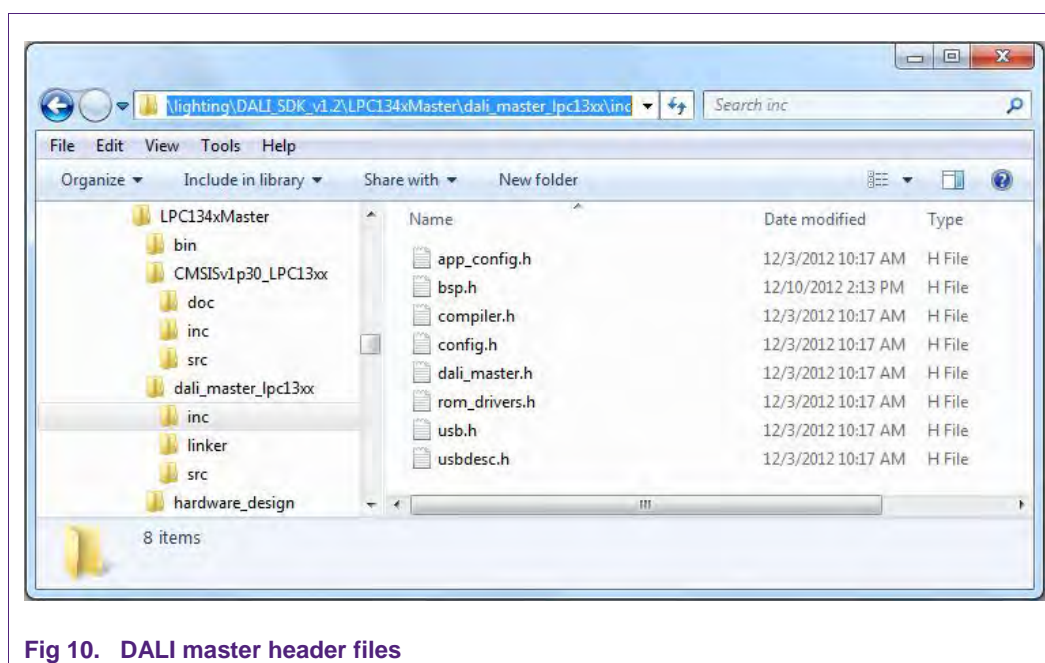


Fig 10. DALI master header files

A brief description of these source code files is shown in [Table 3](#).

Table 3. DALI master source code file description

| File name | Description |
|--------------------|---|
| app_config.h | By means of this file the DALI master application can be configured |
| bsp.c | This file implements the “board support package”, functions for this MCU and board (PCB) |
| bsp.h | Header file describing the exported functions by bsp.c |
| compiler.h | This file contains compiler specific definitions |
| config.h | This file contains USB HID device info configuration settings |
| cr_startup_lpc13.c | Assembly file containing the Reset vector and exception vector table (needed for the LPCXpresso build only) |
| cstartup_M.s | Assembly file containing the Reset vector and exception vector table (needed for the IAR build only) |
| dali_master.c | This file contains the main loop, and DALI bus plus host message handling |
| dali_master.h | This file contains the exported functions of dali_master.c |
| main.c | This file contains the application entry point |
| rom_drivers.h | This file contains setup structures for the USB HID driver in the boot ROM |
| usb.c | This file contains the glue layer to initialize this USB HID driver |
| usb.h | This file contains USB definitions |
| usbdesc.c | This file contains the USB descriptor |
| usbdesc.h | This file contains the USB descriptor definition |

4.7 Building the software

The software tree includes project files for LPCXpresso v5.0.10_1066.

When using LPCXpresso for building the DALI master, use workspace location <your install path>\DALI_Master and import the existing project at the location <your install path>\DALI_Master\dali_master_lpc13xx. Make sure to uncheck the "Copy projects into workspace" checkbox.

Next to LPCXpresso the software tree also includes project files for IAR Embedded Workbench for ARM v6.40. When the IAR workbench is installed, open the project by double clicking the file 'DALI_Master_LPC134x.eww'.

The software can be configured via the source file 'app_config.h', which holds one configuration option as listed in [Table 4](#).

Table 4. DALI master configuration options

| Define | Description |
|------------------------|---------------------|
| LPC_CORE_CLOCKSPEED_HZ | Sets the CPU clock. |

The CPU clock is configured at 48 MHz (a multiple of 12 MHz), which gives more than enough performance needed for the DALI master.

[Table 5](#) shows the firmware sizes (in bytes) of a RELEASE build of the DALI master.

Table 5. DALI master firmware sizes

| Firmware sizes for DALI master | IAR EWARM v6.40 | | LPCXpresso v5.0.10_1066 | |
|--------------------------------|-----------------|-------------|-------------------------|-------------|
| | Flash [Bytes] | RAM [Bytes] | Flash [Bytes] | RAM [Bytes] |
| Release build | 2168 + 108 | 136 | 2280 | 136 |

In the IAR IDE a program stack of 512 bytes is reserved in RAM (not shown in [Table 5](#)); in LPCXpresso this program stack size is not fixed. Further, the USB HID driver in the boot ROM needs 304 bytes in RAM (from address 0x1000 0050 to 0x1000 0180) which is also not shown in [Table 5](#).

5. Summary

This application note describes how to use the NXP LPC1343 microcontroller with integrated USB functionality to act as a USB to DALI device. It shows the hardware and describes the accompanying software. The software is available for the LPCXpresso and IAR development environments.

Creating a complete evaluation setup is described in UM10553 [\[3\]](#) that uses the NXP LPC111x DALI Slave OM13026, see AN11174 [\[4\]](#).

6. Document management

6.1 Abbreviations

Table 6. Abbreviations

| Acronym | Description |
|---------|--|
| CMSIS | Cortex Microcontroller Software Interface Standard |
| CPU | Central Processing Unit |
| CT | Counter Timer |
| GPIO | General Purpose Input/Output |
| HW | Hardware |
| IDE | Integrated Development Environment |
| IRQ | Interrupt Request |
| LED | Light Emitting Diode |
| MCU | Micro Controller Unit |
| NVM | Non Volatile Memory |
| PC | Personal Computer |
| PCB | Printed Circuit Board |
| PIO | Input/Output Pin |
| PLL | Phase Locked Loop |
| SW | Software |
| USB | Universal Serial Bus |

6.2 Referenced documents

- [1] IEC62386-101: Digital addressable lighting interface, General requirements – system, Edition 1.0 2009-6, IEC, 2009.
- [2] UM10375: LPC1311/13/42/43 User manual, Rev. 5, NXP, 21 June 2012.
- [3] UM10553: DALI getting started guide, Rev. 2, NXP, 6 March 2013.
- [4] AN11174: DALI slave using the LPC111x, Rev. 2, NXP, 6 March 2013.

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